

SPECIFICATIONS

Insulation Resistance:	250MΩ at 500V DC
Withstanding Voltage:	500V ACrms for 1 minute
Contact Resistance:	40mΩ max.
Current Rating:	0.5A
Voltage Rating:	50V DC
Operating Temp. Range:	-40°C to +85°C
Mating Cycles:	30 times

MATERIALS AND FINISH

Insulator:	LCP (UL 94V-0)
Contacts:	High Performance Copper Alloy
Contact Plating:	Contact Area - Selective Gold Flash, 15μ" or 30μ" Solder Area - Gold Flash Underplate - Ni

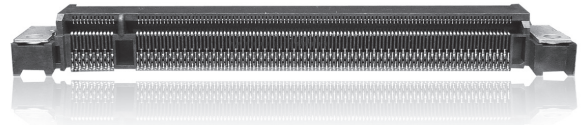
FEATURES

- Transferring High speed data rates to support USB3.0, HDMI, PCIe2.0 and SATA
- Designed for use at Automotive and other rough applications
- Reliable contact design
- Additional fixation of the module with screws at the connector possible
- 230pins, 90°, 0.5mm pitch
- Mating height 5mm
- Production site TS16949 certified
- For transferring of power we advise to use the Power connector (see next page)

PART NUMBER

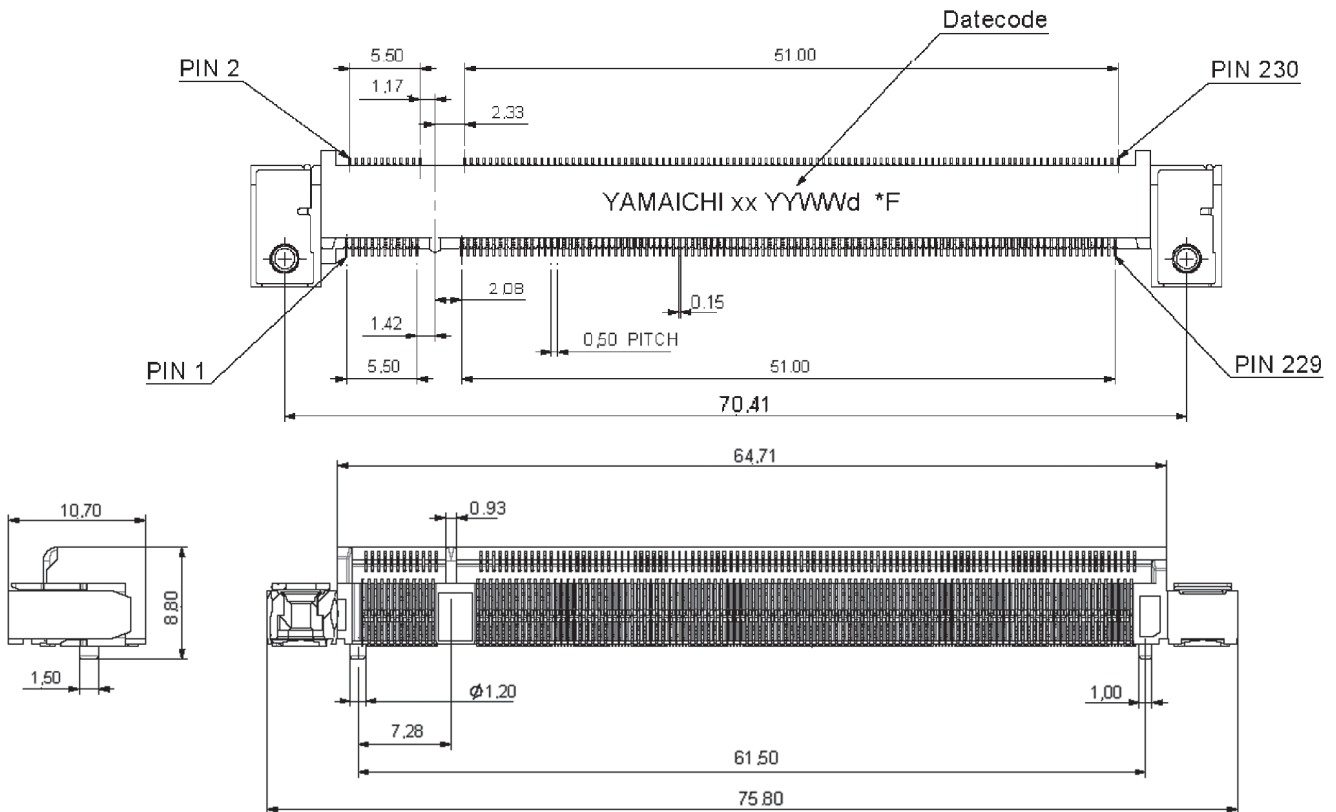
BECHS - 0.5 - 230 - S9 - *F - R - EDC

Series	↑
Pitch: 0.50mm	↑
Pin Count: 230	↑
Orientation: 90°	↑
Contact Area Plating FF = Gold Flash BF = 15μ" Au AF = 30μ" Au	↑
Tape and Reel (300pcs. per reel)	↑
Design No. (internal)	↑



**AUTOMOTIVE
COMPLIANT**

OUTLINE DIMENSIONS



RECOMENDED PCB LAYOUT FOR BEC AND POWER CONNECTOR

